

### **ABSTRACT OF THE DISCLOSURE**

1           A chip size package semiconductor device can have reliable solder mounting and  
2 improved mounting reliability. A semiconductor device (10) of one embodiment can include  
3 a semiconductor chip (1) mounted to a bottom portion (11) of a metal base (10). A metal  
4 base (10) can have side portions (12) with connection electrodes (15) having a surface level  
5 higher than that of electrodes (7 and 8) on a surface of the semiconductor chip (1) by a  
6 difference (d). The semiconductor device (10) can be mounted face down without abutting  
7 the semiconductor chip (1) against a mounting substrate, thereby preventing mechanical  
8 damage to a semiconductor chip (1). At the same time, a solder layer can be formed in the  
9 gap between electrodes (7 and 8) and the mounting substrate, thereby raising the reliability of  
10 the soldering connection.